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Details

Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	32
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega16a-pu

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Special Microcontroller Features
 - Power-on Reset and Programmable Brown-out Detection
 - Internal Calibrated RC Oscillator
 - External and Internal Interrupt Sources
 - Six Sleep Modes: Idle, ADC Noise Reduction, Power-save, Power-down, Standby and Extended Standby
- I/O and Packages
 - 32 Programmable I/O Lines
 - 40-pin PDIP, 44-lead TQFP, and 44-pad QFN/MLF
- Operating Voltages
 - 2.7 5.5V
- Speed Grades
 - 0 16MHz
- Power Consumption @ 1MHz, 3V, and 25°C
 - Active: 0.6mA
 - Idle Mode: 0.2mA
 - Power-down Mode: < 1µA

Program flow is provided by conditional and unconditional jump and call instructions, able to directly address the whole address space. Most AVR instructions have a single 16-bit word format. Every program memory address contains a 16- or 32-bit instruction.

Program Flash memory space is divided in two sections, the Boot program section and the Application Program section. Both sections have dedicated Lock bits for write and read/write protection. The SPM instruction that writes into the Application Flash memory section must reside in the Boot Program section.

During interrupts and subroutine calls, the return address Program Counter (PC) is stored on the Stack. The Stack is effectively allocated in the general data SRAM, and consequently the Stack size is only limited by the total SRAM size and the usage of the SRAM. All user programs must initialize the SP in the reset routine (before subroutines or interrupts are executed). The Stack Pointer SP is read/write accessible in the I/O space. The data SRAM can easily be accessed through the five different addressing modes supported in the AVR architecture.

The memory spaces in the AVR architecture are all linear and regular memory maps.

A flexible interrupt module has its control registers in the I/O space with an additional global interrupt enable bit in the Status Register. All interrupts have a separate interrupt vector in the interrupt vector table. The interrupts have priority in accordance with their interrupt vector position. The lower the interrupt vector address, the higher the priority.

The I/O memory space contains 64 addresses for CPU peripheral functions as Control Registers, SPI, and other I/O functions. The I/O Memory can be accessed directly, or as the Data Space locations following those of the Register File, \$20 - \$5F.

6.2 ALU – Arithmetic Logic Unit

The high-performance AVR ALU operates in direct connection with all the 32 general purpose working registers. Within a single clock cycle, arithmetic operations between general purpose registers or between a register and an immediate are executed. The ALU operations are divided into three main categories – arithmetic, logical, and bit-functions. Some implementations of the architecture also provide a powerful multiplier supporting both signed/unsigned multiplication and fractional format. See the "Instruction Set" section for a detailed description.

6.3 Status Register

The Status Register contains information about the result of the most recently executed arithmetic instruction. This information can be used for altering program flow in order to perform conditional operations. Note that the Status Register is updated after all ALU operations, as specified in the Instruction Set Reference. This will in many cases remove the need for using the dedicated compare instructions, resulting in faster and more compact code.

The Status Register is not automatically stored when entering an interrupt routine and restored when returning from an interrupt. This must be handled by software.

6.3.1 SREG – AVR Status Register



power consumption considerably. This mode has a limited frequency range and it can not be used to drive other clock buffers.

For resonators, the maximum frequency is 8 MHz with CKOPT unprogrammed and 16 MHz with CKOPT programmed. C1 and C2 should always be equal for both crystals and resonators. The optimal value of the capacitors depends on the crystal or resonator in use, the amount of stray capacitance, and the electromagnetic noise of the environment. Some initial guidelines for choosing capacitors for use with crystals are given in Table 8-3. For ceramic resonators, the capacitor values given by the manufacturer should be used.

Figure 8-2. Crystal Oscillator Connections



The Oscillator can operate in three different modes, each optimized for a specific frequency range. The operating mode is selected by the fuses CKSEL3:1 as shown in Table 8-3.

СКОРТ	CKSEL3:1	Frequency Range (MHz)	Recommended Range for Capacitors C1 and C2 for Use with Crystals (pF)
1	101 ⁽¹⁾	0.4 - 0.9	-
1	110	0.9 - 3.0	12 - 22
1	111	3.0 - 8.0	12 - 22
0	101, 110, 111	1.0 ≤	12 - 22

 Table 8-3.
 Crystal Oscillator Operating Modes

Note: 1. This option should not be used with crystals, only with ceramic resonators.

The CKSEL0 Fuse together with the SUT1:0 Fuses select the start-up times as shown in Table 8-4.

CKSEL0	SUT1:0	Start-up Time from Power-down and Power-save	Additional Delay from Reset (V _{CC} = 5.0V)	Recommended Usage
0	00	258 CK ⁽¹⁾	4.1ms	Ceramic resonator, fast rising power
0	01	258 CK ⁽¹⁾	65ms	Ceramic resonator, slowly rising power
0	10	1K CK ⁽²⁾	_	Ceramic resonator, BOD enabled
0	11	1K CK ⁽²⁾	4.1ms	Ceramic resonator, fast rising power
1	00	1K CK ⁽²⁾	65ms	Ceramic resonator, slowly rising power

 Table 8-4.
 Start-up Times for the Crystal Oscillator Clock Selection

Figure 10-3. MCU Start-up, RESET Extended Externally



10.1.3 External Reset

An External Reset is generated by a low level on the $\overline{\text{RESET}}$ pin. Reset pulses longer than the minimum pulse width (see "System and Reset Characteristics" on page 282) will generate a reset, even if the clock is not running. Shorter pulses are not guaranteed to generate a reset. When the applied signal reaches the Reset Threshold Voltage – V_{RST} – on its positive edge, the delay counter starts the MCU after the Time-out period t_{TOUT} has expired.





10.1.4 Brown-out Detection

The ATmega16A has an On-chip Brown-out Detection (BOD) circuit for monitoring the V_{CC} level during operation by comparing it to a fixed trigger level. The trigger level for the BOD can be selected by the fuse BODLEVEL to be 2.7V (BODLEVEL unprogrammed), or 4.0V (BODLEVEL programmed). The trigger level has a hysteresis to ensure spike free Brown-out Detection. The hysteresis on the detection level should be interpreted as V_{BOT} = V_{BOT} + $V_{HYST}/2$ and V_{BOT} = V_{BOT} - $V_{HYST}/2$.

The BOD circuit can be enabled/disabled by the fuse BODEN. When the BOD is enabled (BODEN programmed), and V_{CC} decreases to a value below the trigger level (V_{BOT} in Figure 10-5), the Brown-out Reset is immediately activated. When V_{CC} increases above the trigger level (V_{BOT} in Figure 10-5), the delay counter starts the MCU after the Time-out period t_{TOUT} has expired.

The BOD circuit will only detect a drop in V_{CC} if the voltage stays below the trigger level for longer than t_{BOD} given in "System and Reset Characteristics" on page 282.

Signal Name	PB3/OC0/AIN1	PB2/INT2/AIN0	PB1/T1	PB0/T0/XCK
PUOE	0	0	0	0
PUOV	0	0	0	0
DDOE	0	0	0	0
DDOV	0	0	0	0
PVOE	OC0 ENABLE	0	0	UMSEL
PVOV	OC0	0	0	XCK OUTPUT
DIEOE	0	INT2 ENABLE	0	0
DIEOV	0	1	0	0
DI	-	INT2 INPUT	T1 INPUT	XCK INPUT/T0 INPUT
AIO	AIN1 INPUT	AIN0 INPUT	_	_

Table 12-8. Overriding Signals for Alternate Functions in PB3:PB0

12.3.3 Alternate Functions of Port C

The Port C pins with alternate functions are shown in Table 12-9. If the JTAG interface is enabled, the pull-up resistors on pins PC5(TDI), PC3(TMS) and PC2(TCK) will be activated even if a reset occurs.

Port Pin	Alternate Function
PC7	TOSC2 (Timer Oscillator Pin 2)
PC6	TOSC1 (Timer Oscillator Pin 1)
PC5	TDI (JTAG Test Data In)
PC4	TDO (JTAG Test Data Out)
PC3	TMS (JTAG Test Mode Select)
PC2	TCK (JTAG Test Clock)
PC1	SDA (Two-wire Serial Bus Data Input/Output Line)
PC0	SCL (Two-wire Serial Bus Clock Line)

 Table 12-9.
 Port C Pins Alternate Functions

The alternate pin configuration is as follows:

• TOSC2 – Port C, Bit 7

TOSC2, Timer Oscillator pin 2: When the AS2 bit in ASSR is set (one) to enable asynchronous clocking of Timer/Counter2, pin PC7 is disconnected from the port, and becomes the inverting output of the Oscillator amplifier. In this mode, a Crystal Oscillator is connected to this pin, and the pin can not be used as an I/O pin.

• TOSC1 – Port C, Bit 6

TOSC1, Timer Oscillator pin 1: When the AS2 bit in ASSR is set (one) to enable asynchronous clocking of Timer/Counter2, pin PC6 is disconnected from the port, and becomes the input of the inverting Oscillator amplifier. In this mode, a Crystal Oscillator is connected to this pin, and the pin can not be used as an I/O pin.

A frequency (with 50% duty cycle) waveform output in fast PWM mode can be achieved by setting OC0 to toggle its logical level on each compare match (COM01:0 = 1). The waveform generated will have a maximum frequency of $f_{OC0} = f_{clk_I/O}/2$ when OCR0 is set to zero. This feature is similar to the OC0 toggle in CTC mode, except the double buffer feature of the output compare unit is enabled in the fast PWM mode.

14.7.4 Phase Correct PWM Mode

The phase correct PWM mode (WGM01:0 = 1) provides a high resolution phase correct PWM waveform generation option. The phase correct PWM mode is based on a dual-slope operation. The counter counts repeatedly from BOTTOM to MAX and then from MAX to BOTTOM. In non-inverting Compare Output mode, the Output Compare (OC0) is cleared on the compare match between TCNT0 and OCR0 while upcounting, and set on the compare match while downcounting. In inverting Output Compare mode, the operation is inverted. The dual-slope operation has lower maximum operation frequency than single slope operation. However, due to the symmetric feature of the dual-slope PWM modes, these modes are preferred for motor control applications.

The PWM resolution for the phase correct PWM mode is fixed to eight bits. In phase correct PWM mode the counter is incremented until the counter value matches MAX. When the counter reaches MAX, it changes the count direction. The TCNT0 value will be equal to MAX for one timer clock cycle. The timing diagram for the phase correct PWM mode is shown on Figure 14-7. The TCNT0 value is in the timing diagram shown as a histogram for illustrating the dual-slope operation. The diagram includes non-inverted and inverted PWM outputs. The small horizontal line marks on the TCNT0 slopes represent compare matches between OCR0 and TCNT0.



Figure 14-7. Phase Correct PWM Mode, Timing Diagram

The Timer/Counter Overflow Flag (TOV0) is set each time the counter reaches BOTTOM. The Interrupt Flag can be used to generate an interrupt each time the counter reaches the BOTTOM value.

In phase correct PWM mode, the compare unit allows generation of PWM waveforms on the OC0 pin. Setting the COM01:0 bits to 2 will produce a non-inverted PWM. An inverted PWM output can be generated by setting the COM01:0 to 3 (see Table 14-5 on page 81). The actual OC0 value will only be visible on the port pin if the data direction for the port pin is set as output. The PWM waveform is generated by clearing (or setting) the OC0 Register at the compare match between OCR0 and TCNT0 when the counter increments, and setting (or

A frequency (with 50% duty cycle) waveform output in fast PWM mode can be achieved by setting OC2 to toggle its logical level on each compare match (COM21:0 = 1). The waveform generated will have a maximum frequency of $f_{oc2} = f_{clk_l/O}/2$ when OCR2 is set to zero. This feature is similar to the OC2 toggle in CTC mode, except the double buffer feature of the output compare unit is enabled in the fast PWM mode.

17.7.4 Phase Correct PWM Mode

The phase correct PWM mode (WGM21:0 = 1) provides a high resolution phase correct PWM waveform generation option. The phase correct PWM mode is based on a dual-slope operation. The counter counts repeatedly from BOTTOM to MAX and then from MAX to BOTTOM. In non-inverting Compare Output mode, the Output Compare (OC2) is cleared on the compare match between TCNT2 and OCR2 while upcounting, and set on the compare match while downcounting. In inverting Output Compare mode, the operation is inverted. The dual-slope operation has lower maximum operation frequency than single slope operation. However, due to the symmetric feature of the dual-slope PWM modes, these modes are preferred for motor control applications.

The PWM resolution for the phase correct PWM mode is fixed to 8 bits. In phase correct PWM mode the counter is incremented until the counter value matches MAX. When the counter reaches MAX, it changes the count direction. The TCNT2 value will be equal to MAX for one timer clock cycle. The timing diagram for the phase correct PWM mode is shown on Figure 17-7. The TCNT2 value is in the timing diagram shown as a histogram for illustrating the dual-slope operation. The diagram includes non-inverted and inverted PWM outputs. The small horizontal line marks on the TCNT2 slopes represent compare matches between OCR2 and TCNT2.





The Timer/Counter Overflow Flag (TOV2) is set each time the counter reaches BOTTOM. The Interrupt Flag can be used to generate an interrupt each time the counter reaches the BOTTOM value.

In phase correct PWM mode, the compare unit allows generation of PWM waveforms on the OC2 pin. Setting the COM21:0 bits to 2 will produce a non-inverted PWM. An inverted PWM output can be generated by setting the COM21:0 to 3 (see Table 17-5 on page 126). The actual OC2 value will only be visible on the port pin if the data direction for the port pin is set as output. The PWM waveform is generated by clearing (or setting) the OC2 Register at the compare match between OCR2 and TCNT2 when the counter increments, and setting (or

17.11 Register Description



17.11.1 TCCR2 – Timer/Counter Control Register

• Bit 7 – FOC2: Force Output Compare

The FOC2 bit is only active when the WGM bits specify a non-PWM mode. However, for ensuring compatibility with future devices, this bit must be set to zero when TCCR2 is written when operating in PWM mode. When writing a logical one to the FOC2 bit, an immediate compare match is forced on the waveform generation unit. The OC2 output is changed according to its COM21:0 bits setting. Note that the FOC2 bit is implemented as a strobe. Therefore it is the value present in the COM21:0 bits that determines the effect of the forced compare.

A FOC2 strobe will not generate any interrupt, nor will it clear the timer in CTC mode using OCR2 as TOP.

The FOC2 bit is always read as zero.

• Bit 3, 6 – WGM2[1:0]: Waveform Generation Mode

These bits control the counting sequence of the counter, the source for the maximum (TOP) counter value, and what type of waveform generation to be used. Modes of operation supported by the Timer/Counter unit are: Normal mode, Clear Timer on Compare match (CTC) mode, and two types of Pulse Width Modulation (PWM) modes. See Table 17-2 and "Modes of Operation" on page 116.

Mode	WGM21 (CTC2)	WGM20 (PWM2)	Timer/Counter Mode of Operation	ТОР	Update of OCR2	TOV2 Flag Set on
0	0	0	Normal	0xFF	Immediate	MAX
1	0	1	PWM, Phase Correct	0xFF	TOP	BOTTOM
2	1	0	CTC	OCR2	Immediate	MAX
3	1	1	Fast PWM	0xFF	BOTTOM	MAX

 Table 17-2.
 Waveform Generation Mode Bit Description⁽¹⁾

Note: 1. The CTC2 and PWM2 bit definition names are now obsolete. Use the WGM21:0 definitions. However, the functionality and location of these bits are compatible with previous versions of the timer.

• Bit 5:4 – COM21:0: Compare Match Output Mode

These bits control the Output Compare pin (OC2) behavior. If one or both of the COM21:0 bits are set, the OC2 output overrides the normal port functionality of the I/O pin it is connected to. However, note that the Data Direction Register (DDR) bit corresponding to OC2 pin must be set in order to enable the output driver.

```
Assembly Code Example<sup>(1)</sup>
       USART ReadUCSRC:
               ; Read UCSRC
              in
                             r16,UBRRH
               in
                             r16,UCSRC
              ret
C Code Example<sup>(1)</sup>
       unsigned char USART_ReadUCSRC( void )
       ł
              unsigned char ucsrc;
               /* Read UCSRC */
              ucsrc = UBRRH;
              ucsrc = UCSRC;
              return ucsrc;
       }
```

Note: 1. See "About Code Examples" on page 7.

The assembly code example returns the UCSRC value in r16.

Reading the UBRRH contents is not an atomic operation and therefore it can be read as an ordinary register, as long as the previous instruction did not access the register location.

19.11 Register Description

19.11.1 UDR - USART I/O Data Register



The USART Transmit Data Buffer Register and USART Receive Data Buffer Registers share the same I/O address referred to as USART Data Register or UDR. The Transmit Data Buffer Register (TXB) will be the destination for data written to the UDR Register location. Reading the UDR Register location will return the contents of the Receive Data Buffer Register (RXB).

For 5-, 6-, or 7-bit characters the upper unused bits will be ignored by the Transmitter and set to zero by the Receiver.

The transmit buffer can only be written when the UDRE Flag in the UCSRA Register is set. Data written to UDR when the UDRE Flag is not set, will be ignored by the USART Transmitter. When data is written to the transmit buffer, and the Transmitter is enabled, the Transmitter will load the data into the transmit Shift Register when the Shift Register is empty. Then the data will be serially transmitted on the TxD pin.

The receive buffer consists of a two level FIFO. The FIFO will change its state whenever the receive buffer is accessed. Due to this behavior of the receive buffer, do not use read modify write instructions (SBI and CBI) on this location. Be careful when using bit test instructions (SBIC and SBIS), since these also will change the state of the FIFO.

• Bit 11:0 – UBRR11:0: USART Baud Rate Register

This is a 12-bit register which contains the USART baud rate. The UBRRH contains the four most significant bits, and the UBRRL contains the 8 least significant bits of the USART baud rate. Ongoing transmissions by the transmitter and receiver will be corrupted if the baud rate is changed. Writing UBRRL will trigger an immediate update of the baud rate prescaler.

19.12 Examples of Baud Rate Setting

For standard crystal and resonator frequencies, the most commonly used baud rates for asynchronous operation can be generated by using the UBRR settings in Table 19-9. UBRR values which yield an actual baud rate differing less than 0.5% from the target baud rate, are bold in the table. Higher error ratings are acceptable, but the receiver will have less noise resistance when the error ratings are high, especially for large serial frames (see "Asynchronous Operational Range" on page 154). The error values are calculated using the following equation:

$$Error[\%] = \left(\frac{BaudRate_{Closest Match}}{BaudRate} - 1\right) \bullet 100\%$$

		$f_{osc} = 1.0$	0000MHz			$f_{osc} = 1.8$	432MHz			$f_{osc} = 2.0$	0000MHz	
Baud Rate	U2X	ζ = 0	U2X	(= 1	U2X	(= 0	U2X	(= 1	U2>	(= 0	U2X	(= 1
(bps)	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error	UBRR	Error
2400	25	0.2%	51	0.2%	47	0.0%	95	0.0%	51	0.2%	103	0.2%
4800	12	0.2%	25	0.2%	23	0.0%	47	0.0%	25	0.2%	51	0.2%
9600	6	-7.0%	12	0.2%	11	0.0%	23	0.0%	12	0.2%	25	0.2%
14.4k	3	8.5%	8	-3.5%	7	0.0%	15	0.0%	8	-3.5%	16	2.1%
19.2k	2	8.5%	6	-7.0%	5	0.0%	11	0.0%	6	-7.0%	12	0.2%
28.8k	1	8.5%	3	8.5%	3	0.0%	7	0.0%	3	8.5%	8	-3.5%
38.4k	1	-18.6%	2	8.5%	2	0.0%	5	0.0%	2	8.5%	6	-7.0%
57.6k	0	8.5%	1	8.5%	1	0.0%	3	0.0%	1	8.5%	3	8.5%
76.8k	_	_	1	-18.6%	1	-25.0%	2	0.0%	1	-18.6%	2	8.5%
115.2k	_	_	0	8.5%	0	0.0%	1	0.0%	0	8.5%	1	8.5%
230.4k	_	_	_	_	_	-	0	0.0%	_	-	_	_
250k	_	_	_	_	_	-	—	_	_	-	0	0.0%
Max ⁽¹⁾	62.5	kbps	125	kbps	115.2	2kbps	230.4	kbps	125	kbps	250	kbps

Table 19-9. Examples of UBRR Settings for Commonly Used Oscillator Frequencies

1. UBRR = 0, Error = 0.0%

Figure 20-12. Formats and States in the Master Transmitter Mode



20.7.2 Master Receiver Mode

In the Master Receiver mode, a number of data bytes are received from a Slave Transmitter (see Figure 20-13). In order to enter a Master mode, a START condition must be transmitted. The format of the following address packet determines whether Master Transmitter or Master Receiver mode is to be entered. If SLA+W is transmitted, MT mode is entered, if SLA+R is transmitted, MR mode is entered. All the status codes mentioned in this section assume that the prescaler bits are zero or are masked to zero.

21. Analog Comparator

The Analog Comparator compares the input values on the positive pin AIN0 and negative pin AIN1. When the voltage on the positive pin AIN0 is higher than the voltage on the negative pin AIN1, the Analog Comparator Output, ACO, is set. The comparator's output can be set to trigger the Timer/Counter1 Input Capture function. In addition, the comparator can trigger a separate interrupt, exclusive to the Analog Comparator. The user can select Interrupt triggering on comparator output rise, fall or toggle. A block diagram of the comparator and its surrounding logic is shown in Figure 21-1.





Notes: 1. See Table 1 on page 193.

2. Refer to Figure 1-1 on page 3 and Table 12-6 on page 57 for Analog Comparator pin placement.

21.1 Analog Comparator Multiplexed Input

It is possible to select any of the ADC7:0 pins to replace the negative input to the Analog Comparator. The ADC multiplexer is used to select this input, and consequently, the ADC must be switched off to utilize this feature. If the Analog Comparator Multiplexer Enable bit (ACME in SFIOR) is set and the ADC is switched off (ADEN in ADCSRA is zero), MUX2:0 in ADMUX select the input pin to replace the negative input to the Analog Comparator, as shown in Table 1. If ACME is cleared or ADEN is set, AIN1 is applied to the negative input to the Analog Comparator.

ACME	ADEN	MUX2:0	Analog Comparator Negative Input
0	х	xxx	AIN1
1	1	xxx	AIN1
1	0	000	ADC0
1	0	001	ADC1
1	0	010	ADC2
1	0	011	ADC3

	Table 1.	Analog	Comparator	Multiplexed	Input
--	----------	--------	------------	-------------	-------

Figure 25-1. Read-While-Write vs. No Read-While-Write



• Bit 2 – PGWRT: Page Write

If this bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles executes Page Write, with the data stored in the temporary buffer. The page address is taken from the high part of the Z-pointer. The data in R1 and R0 are ignored. The PGWRT bit will auto-clear upon completion of a page write, or if no SPM instruction is executed within four clock cycles. The CPU is halted during the entire page write operation if the NRWW section is addressed.

• Bit 1 – PGERS: Page Erase

If this bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles executes Page Erase. The page address is taken from the high part of the Z-pointer. The data in R1 and R0 are ignored. The PGERS bit will auto-clear upon completion of a page erase, or if no SPM instruction is executed within four clock cycles. The CPU is halted during the entire page write operation if the NRWW section is addressed.

• Bit 0 – SPMEN: Store Program Memory Enable

This bit enables the SPM instruction for the next four clock cycles. If written to one together with either RWWSRE, BLBSET, PGWRT' or PGERS, the following SPM instruction will have a special meaning, see description above. If only SPMEN is written, the following SPM instruction will store the value in R1:R0 in the temporary page buffer addressed by the Z-pointer. The LSB of the Z-pointer is ignored. The SPMEN bit will auto-clear upon completion of an SPM instruction, or if no SPM instruction is executed within four clock cycles. During page erase and page write, the SPMEN bit remains high until the operation is completed.

Writing any other combination than "10001", "01001", "00101", "00011" or "00001" in the lower five bits will have no effect.

25.7 Addressing the Flash during Self-Programming

Bit	15	14	13	12	11	10	9	8
ZH (R31)	Z15	Z14	Z13	Z12	Z11	Z10	Z9	Z8
ZL (R30)	Z7	Z6	Z5	Z4	Z3	Z2	Z1	Z0
	7	6	5	4	3	2	1	0

The Z-pointer is used to address the SPM commands.

Since the Flash is organized in pages (see Table 26-5 on page 254), the Program Counter can be treated as having two different sections. One section, consisting of the least significant bits, is addressing the words within a page, while the most significant bits are addressing the pages. This is shown in Figure 25-3. Note that the Page Erase and Page Write operations are addressed independently. Therefore it is of major importance that the Boot Loader software addresses the same page in both the Page Erase and Page Write operation. Once a programming operation is initiated, the address is latched and the Z-pointer can be used for other operations.

The only SPM operation that does not use the Z-pointer is Setting the Boot Loader Lock bits. The content of the Z-pointer is ignored and will have no effect on the operation. The LPM instruction does also use the Z pointer to store the address. Since this instruction addresses the Flash byte by byte, also the LSB (bit Z0) of the Z-pointer is used.

25.8.10 Preventing Flash Corruption

During periods of low $V_{CC,}$ the Flash program can be corrupted because the supply voltage is too low for the CPU and the Flash to operate properly. These issues are the same as for board level systems using the Flash, and the same design solutions should be applied.

A Flash program corruption can be caused by two situations when the voltage is too low. First, a regular write sequence to the Flash requires a minimum voltage to operate correctly. Secondly, the CPU itself can execute instructions incorrectly, if the supply voltage for executing instructions is too low.

Flash corruption can easily be avoided by following these design recommendations (one is sufficient):

- 1. If there is no need for a Boot Loader update in the system, program the Boot Loader Lock bits to prevent any Boot Loader software updates.
- 2. Keep the AVR RESET active (low) during periods of insufficient power supply voltage. This can be done by enabling the internal Brown-out Detector (BOD) if the operating voltage matches the detection level. If not, an external low V_{CC} Reset Protection circuit can be used. If a reset occurs while a write operation is in progress, the write operation will be completed provided that the power supply voltage is sufficient.
- Keep the AVR core in Power-down Sleep mode during periods of low V_{CC}. This will prevent the CPU from attempting to decode and execute instructions, effectively protecting the SPMCR Register and thus the Flash from unintentional writes.

25.8.11 Programming Time for Flash when using SPM

The Calibrated RC Oscillator is used to time Flash accesses. Table 25-5 shows the typical programming time for Flash accesses from the CPU.

Table 25-5. SPM Programming Time.

Symbol	Min Programming Time	Max Programming Time
Flash write (Page Erase, Page Write, and write Lock bits by SPM)	3.7 ms	4.5 ms

25.8.12 Simple Assembly Code Example for a Boot Loader

;-the routine writes one page of data from RAM to Flash ; the first data location in RAM is pointed to by the Y pointer ; the first data location in Flash is pointed to by the Z pointer ;-error handling is not included ;-the routine must be placed inside the boot space ; (at least the Do_spm sub routine). Only code inside NRWW section can ; be read during self-programming (page erase and page write). ;-registers used: r0, r1, temp1 (r16), temp2 (r17), looplo (r24), ; loophi (r25), spmcrval (r20) ; storing and restoring of registers is not included in the routine ; register usage can be optimized at the expense of code size ;-It is assumed that either the interrupt table is moved to the Boot ; loader section or that the interrupts are disabled. PAGESIZEB = PAGESIZE*2 ; PAGESIZEB is page size in .equ BYTES, not ; words .org SMALLBOOTSTART Write_page: ; page erase spmcrval, (1<<PGERS) | (1<<SPMEN)</pre> ldi call Do_spm ; re-enable the RWW section

Figure 26-13. Virtual Flash Page Load Register



26.10.12 Virtual Flash Page Read Register

The Virtual Flash Page Read Register is a virtual scan chain with length equal to the number of bits in one Flash page plus 8. Internally the Shift Register is 8-bit, and the data are automatically transferred from the Flash data page byte by byte. The first 8 cycles are used to transfer the first byte to the internal Shift Register, and the bits that are shifted out during these 8 cycles should be ignored. Following this initialization, data are shifted out starting with the LSB of the first instruction in the page and ending with the MSB of the last instruction in the page. This provides an efficient way to read one full Flash page to verify programming.





26.10.13 Programming Algorithm

All references below of type "1a", "1b", and so on, refer to Table 26-14.

	Description	Mode	Min	Тур	Max	
1	SCK period	Master		See Table 18-5		
2	SCK high/low	Master		50% duty cycle		
3	Rise/Fall time	Master		3.6		
4	Setup	Master		10		
5	Hold	Master		10		
6	Out to SCK	Master		0.5 • t _{sск}		ns
7	SCK to out	Master		10		
8	SCK to out high	Master		10		
9	SS low to out	Slave		15		
10	SCK period	Slave	4 • t _{SCK}			
11	SCK high/low	Slave	2 • t _{SCK}			
12	Rise/Fall time	Slave			1.6	μs
13	Setup	Slave	10			
14	Hold	Slave	10			
15	SCK to out	Slave		15		
16	SCK to \overline{SS} high	Slave	20			115
17	SS high to tri-state	Slave		10		
18	SS low to SCK	Slave	2 • t _{SCK}			

Table 27-5.SPI Timing Parameters

Figure 27-6. SPI Interface Timing Requirements (Master Mode)



Figure 28-20. I/O Pin Pull-Up Resistor Current vs. Input Voltage ($V_{CC} = 2.7V$)



Figure 28-21. Reset Pull-Up Resistor Current vs. Reset Pin Voltage (V_{CC} = 5V)







Figure 28-39. Calibrated 8MHz RC Oscillator Frequency vs. Osccal Value



34. Datasheet Revision History

Please note that the referring page numbers in this section are referred to this document. The referring revision in this section are referring to the document revision.

Rev. 8154C -07/2014

- 1. Atmel brand style guide and datasheet template of 2014-0502 updated in datasheet including the last page.
- 2. Updated the Ordering Code to include Tape & Reel part numbers.
- 3. Removed notes 6 and 7 concerning actual low period in Table 27-4 on page 283.
- 4. Changed notes 3, 4 and 5, removed note 6 concerning TQFP/MLF packages in Section 27.2 "DC Characteristics" on page 279

Rev. 8154B - 07/09

- 1. Updated "Errata" on page 328.
- 2. Updated the last page with Atmel's new addresses.

Rev. 8154A - 06/08

1. Initial revision (Based on the ATmega16/L datasheet revision 2466R-AVR-05/08)

Changes done compared ATmega16/L datasheet revision 2466R-AVR-05/08:

- Updated description in "Stack Pointer" on page 11.
- All Electrical characteristics is moved to "Electrical Characteristics" on page 279.
- Register descriptions are moved to sub sections at the end of each chapter.
- Added "Speed Grades" on page 281.
- New graphs in "Typical Characteristics" on page 290.
- New "Ordering Information" on page 324.